

# Site-Specific Information

## FY2001 Site News

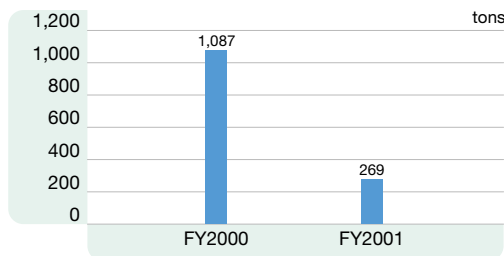
### Facilities achieving zero emissions

The Casio Group defines landfilling no more than 1% of one's wastes as zero emissions, which in FY2001 was achieved by the following three facilities.

- Kofu Casio (Head Office)
- Kofu Casio (Ichinomiya)
- Casio Micronics (Yamanashi)

The use of wastes in eco-cement and the sorting and crushing of waste plastic to make it usable as blast furnace feedstock substantially reduced the amount of landfilled waste by the group, from 1,087 t in FY2000 to 269 t in FY2001.

### Entire Group's landfilled wastes



### Commendation Received from Director-General of Agency of Natural Resources and Energy

Kochi Casio received a commendation (electricity category) from the director-general of the Agency of Natural Resources and Energy as a plant with superior energy management. The plant was applauded for its efforts for energy conservation and management, and for the energy efficiency of its newly built 3rd Plant.



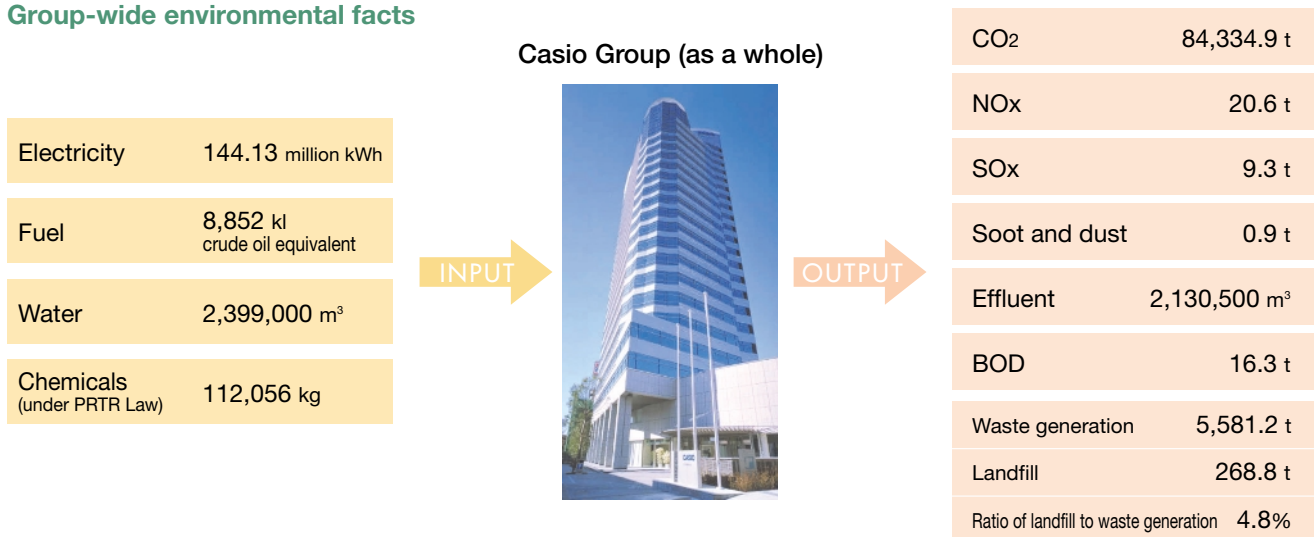
### CO<sub>2</sub> emissions per unit manufactured

FY2001 group-wide CO<sub>2</sub> emissions per unit manufactured rose from 0.423 t CO<sub>2</sub>/¥1 million to 0.504 t CO<sub>2</sub>/¥1 million. The cause was trial operation and adjustments at Casio Micronics (Yamanashi facility) and facility enlargement at Kochi Casio. Once production reaches the planned level, emission per unit manufactured is expected to drop below the 1990 level.

Please see this Web page for details on environmental performance.

URL : <http://www.casio.co.jp/env/activity/performance.html>

## Group-wide environmental facts



### Glossary

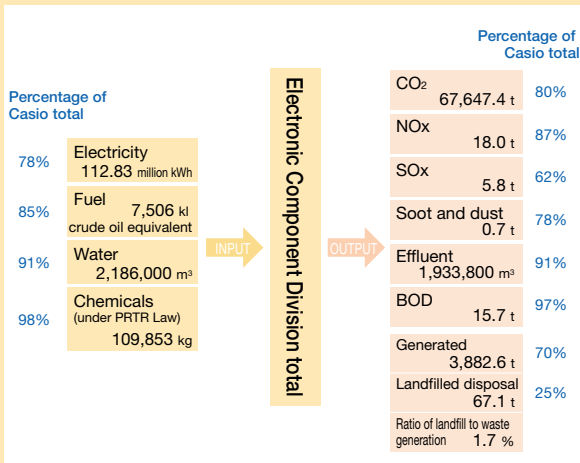
#### Zero emissions

If the annual amount of wastes given final disposal divided by the amount of wastes generated in that same

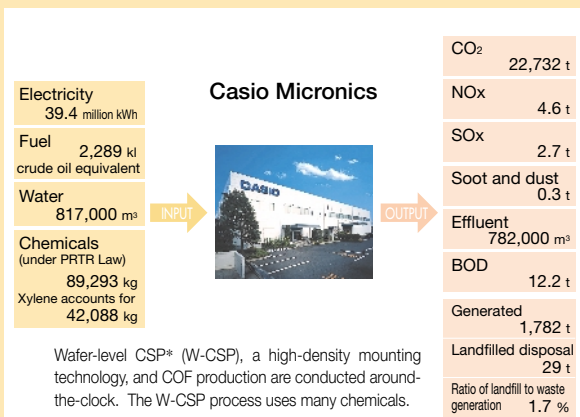
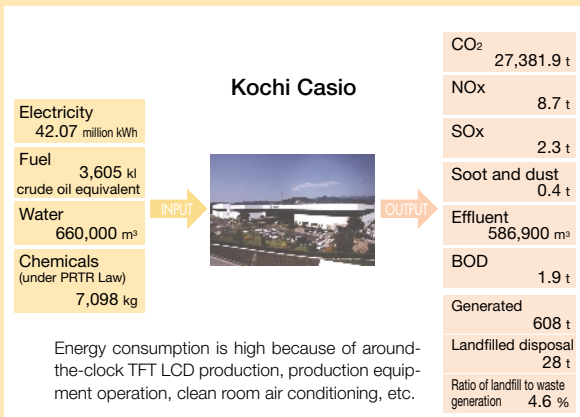
year yields a value of under 1%, the unit generating the wastes is considered to have achieved zero emissions.

Casio's business can be broadly categorized into an Electronic Component Division and an Electronics Equipment Division.

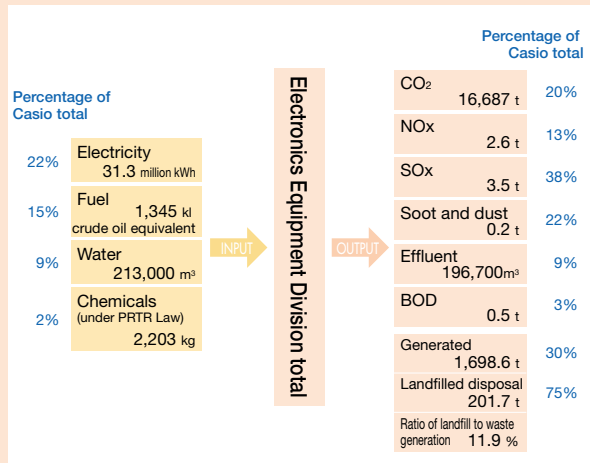
### Electronic Component Division



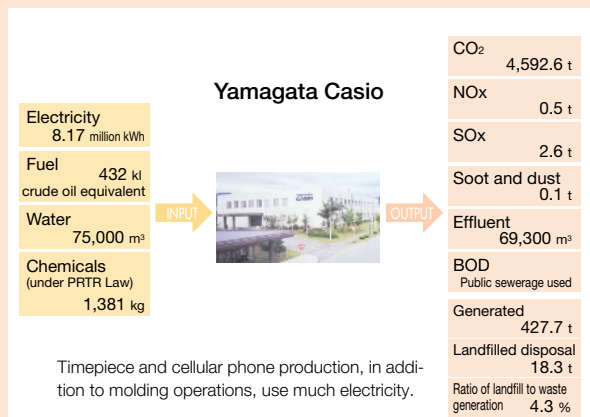
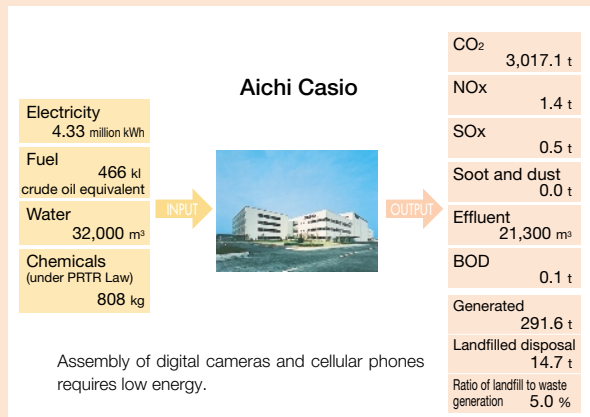
Data for Kochi Casio and Casio Micronics are presented below as typical examples of the Electronic Component Division.



### Electronics Equipment Division



Data for Aichi Casio and Yamagata Casio are presented below as typical examples of the Electronics Equipment Division.



### Glossary

#### Wafer-level CSP

Wafer-level CSP is an advanced technology making it possible, as an LSI packaging process, for copper

rewiring and formation of terminals to be performed with resin sealing in the wafer form.